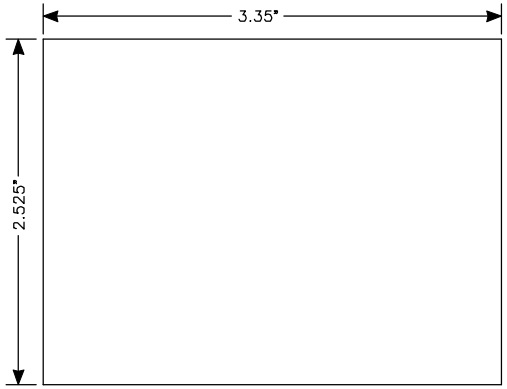
NOTES: UNLESS OTHERWISED SPECIFIED

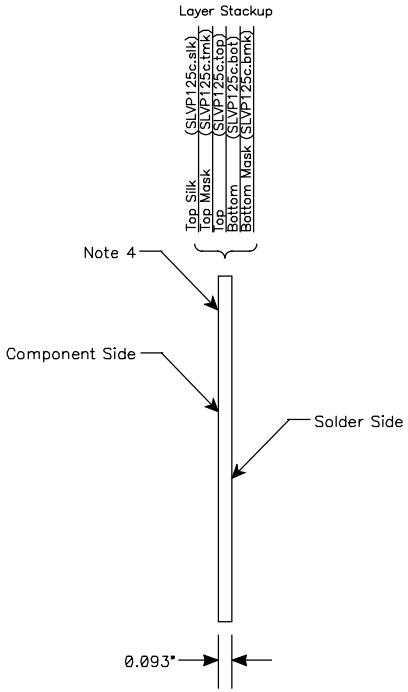
1. Interpret in accordance with DOD-STD-100, ANSI Y14.5, and IPC-T-50.
2. Soldermask over bare copper per IPC-SM-840, Class 3, Type A, liquid (preferred)/dry (acceptable), 0.001 min, both sides. Plated thru-hole pad areas to be free and clear of soldermask, color to be green.
3. Tin-lead plate or solder coat over all exposed copper areas and holes not covered by soldermask.
4. Silkscreen this side over soldermask, using white non-conductive epoxy or enamel.
5. Basic grid increment in X and Y axis is 0.005 at 1/1 from datum.
6. Finished conductor width and spacing 0.010 min.
7. Finished annular ring 0.005 min.
8. All holes plated thru and hold diameters are after plating.
9. Material 0.093 thk, double-sided, FR-4, 2-oz copper, board material must be U.L. recognized with a U.L. flammability class rating of 94V-0.
10. Vendor must be U.L. approved and have their U.L. recognition symbol etched on each PCB in such a manner as to not interfere with any existing etch or holes.

REVISIONS

DRAWING ON CAD, DO NOT MANUALLY UPDATE

REV	DESCRIPTION	DATE	APPROVED
A	New Release	02/17/99	
B	Corrections	02/24/99	
C	Corrections	05/26/99	
D	Short on C1+ and open on C1-.	08/20/99	





SYMBOL	QTY	SIZE	REMARKS
◇	4	0.140" +/- 0.005"	Plated
⊡	4	0.073" +/- 0.003"	Plated
⋈	8	0.046" +/- 0.003"	Plated
⧖	8	0.040" +/- 0.003"	Plated
⊤	82	0.038" +/- 0.003"	Plated
Y	12	0.028" +/- 0.003"	Plated
X	24	0.024" +/- 0.003"	Plated
+	41	0.018" +/- 0.003"	Plated

HOLE CHART

Texas Instruments

Title: FABRICATION, SLVP125

Size	Number	Rev
B		D

Date 09/10/99 | Drawn by P. Rogers

Filename P125dFab.sch | Sheet 1 of 1